507310342 05/31/2022

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	

CONVEYING PARTY DATA

Name	Execution Date
SHIH-HSIUNG HUANG	05/23/2022

RECEIVING PARTY DATA

Name:	REALTEK SEMICONDUCTOR CORPORATION
Street Address:	NO. 2, INNOVATION ROAD II, HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	Taiwan ROC
Postal Code:	300

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	17828472	

CORRESPONDENCE DATA

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NAME OF SUBMITTER:	JUSTIN KING
SIGNATURE:	/Justin King/
DATE SIGNED:	05/31/2022

Total Attachments: 1 source=a#page1.tif

PATENT 507310342 REEL: 060055 FRAME: 0908

ASSIGNMENT

WHEREAS, I(we), SHIH-HSIUNG HUANG whose post office address(es) appear(s) below, hereinafter referred to as ASSIGNOR, have invented certain new and useful invention entitled.

Bootstrapped switch

(hereinafter referred to as the INVENTION) for which an a is executed on even date herewith unless at least one of the United States Design Patent was executed on: Grid Inc. Serial No.:	e following is checked:	s Letters Patent /Utility Patent
☐ established by PCT International Patent Applicat	ion No.: filed:	designating the
United States of America issued on as U.S. Patent No).:	
WHEREAS, REALTEK SEMICONDUCTOR CORPORTION Road II, Hsinchu Science Park, Hsinchu 3 is desirous of acquiring the entire right, title and interest it possessions;	DRATION whose post off 00, Taiwan (R.O.C.) here	inafter referred to as ASSIGNEE,
NOW, THEREFORE, for good and valuable consider ASSIGNOR, by these presents do sell, assign and transfer and to said INVENTION and application throughout the Patent granted on any division, continuation, continuation terms for which the same may be granted, including all pre-	unto said ASSIGNEE, the United States of America in-part and reissue of sai	entire right, title, and interest in including any and all Letters d application for the full term or
ASSIGNOR further covenants that no assignments, so or entered into which would conflict with this Assignment		rance has been or will be made
ALSO, ASSIGNOR hereby agrees to execute any docu filing, prosecution and maintenance of said application of said INVENTION, including additional documents that massaid INVENTION, all without further consideration. AS ASSIGNEE'S expense, to identify and communicate to ASCONCETTION that are within ASSIGNOR'S pot testimony on behalf of ASSIGNEE that lawfully may be maintenance, litigation and defense of any patent applies instrument. ASSIGNOR'S obligations under this instrument administrators and other legal representatives.	or any other patent applicated by the required to affirm the SIGNOR also agrees, with the SIGNEE at ASSIGNEE's requiressession or control, and to be required of ASSIGNOR dication or patent encomp	ation(s) in the United States for the rights of ASSIGNEE in and to the put further consideration and at the theorem in the provide further assurances and the respect of the prosecution that assurance in the prosecution that the terms of this
ALSO, ASSIGNOR hereby authorizes and requests the and all Letters Patent referred to above to ASSIGNEE, as the same, for ASSIGNEE'S sole use and behoof; and for the successors, to the full end of the term for which such L same would have been held by ASSIGNOR had this assign	he ASSIGNEE of the entire the use and behoof of ASSIG etters Patent may be gran	right, title and interest in and to GNEE'S legal representatives and ted, as fully and entirely as the
ASSIGNOR NAME SHIH-HSIUNG HUANG	Address No. 2, Innovation Ros Hsinchu 300, Taiwan	ud II, Hsinchu Science Park, (R.O.C.)

Date of Signature

Name of Witness (optional)

Signature of Witness (Optional)

PATENT REEL: 060055 FRAME: 0909

May 23, 2022

RECORDED: 05/31/2022

Signature of Assignor

Name of Witness (optional)

Signature of Witness (optional)